Binary to 1-8 Decoder (Low)

Description

The MC10H161 provides parallel decoding of a three bit binary word to one of eight lines. The MC10H161 is useful in high-speed multiplexer/demultiplexer applications.

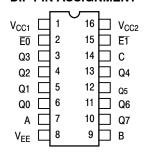
The MC10H161 is designed to decode a three bit input word to one of eight output lines. The MC10H161 output will be low when selected while all other output are high. The enable inputs, when either or both are high, force all outputs high.

The MC10H161 is a true parallel decoder. This eliminates unequal parallel path delay times found in other decoder designs. These devices are ideally suited for multiplexer/demultiplexer applications.

Features

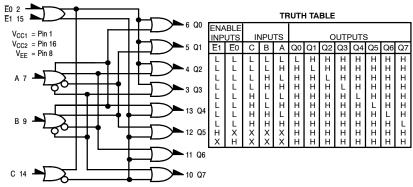
- Propagation Delay, 1.0 ns Typical
- Power Dissipation, 315 mW Typical (same as MECL 10KTM)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- Pb-Free Packages are Available*

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

LOGIC DIAGRAM



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



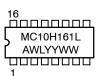
ON Semiconductor®

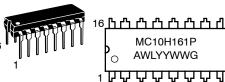
http://onsemi.com

MARKING DIAGRAMS*



CDIP-16 L SUFFIX CASE 620A

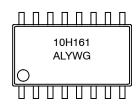




PDIP-16 P SUFFIX CASE 648

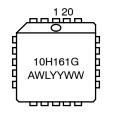


SOEIAJ-16 CASE 966





PLLC-20 FN SUFFIX CASE 775



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G = Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Table 1. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to V _{EE}	Vdc
l _{out}	Output Current – Continuous – Surge	50 100	mA
T _A	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range - Plastic - Ceramic	-55 to +150 -55 to +165	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V $\pm 5\%$) (Note 1)

		0 °		25 °		75 °		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
Ι _Ε	Power Supply Current	-	84	-	76	=	84	mA
I _{inH}	Input Current High	-	465	-	275	-	275	μΑ
I _{inL}	Input Current Low	0.5	-	0.5	-	0.3	=	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

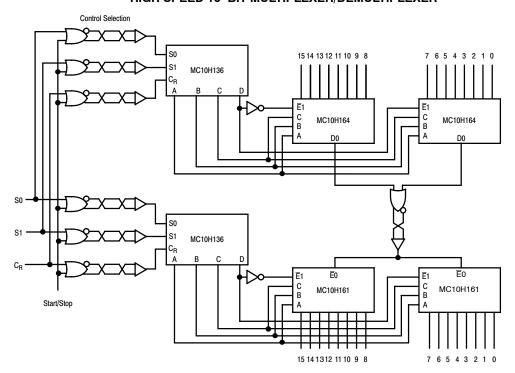
Each MECL 10HTM series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to -2.0 V.

Table 3. AC PARAMETERS

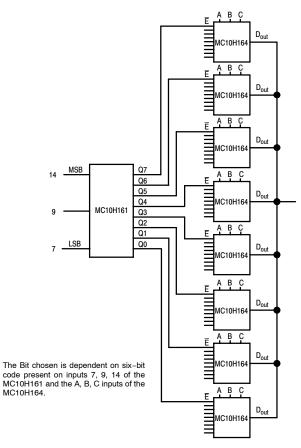
		0) °	2	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay Data Enable	0.6 0.8	2.0 2.3	0.65 0.8	2.1 2.4	0.7 0.9	2.2 2.5	ns
t _r	Rise Time	0.55	1.7	0.65	1.8	0.7	1.9	ns
t _f	Fall Time	0.55	1.7	0.65	1.8	0.7	1.9	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

TYPICAL APPLICATIONS HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



1-OF-64 LINE MULTIPLEXER



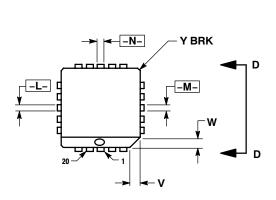
ORDERING INFORMATION

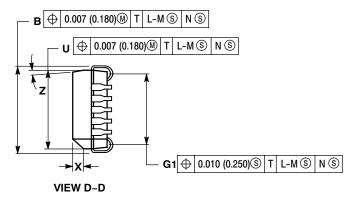
Device	Package	Shipping [†]
MC10H161FN	PLLC-20	46 Units / Rail
MC10H161FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H161FNR2	PLLC-20	500 / Tape & Reel
MC10H161FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H161L	CDIP-16	25 Unit / Rail
MC10H161M	SOEIAJ-16	50 Unit / Rail
MC10H161MG	SOEIAJ-16 (Pb-Free)	50 Unit / Rail
MC10H161MEL	SOEIAJ-16	2000 / Tape & Reel
MC10H161MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC10H161P	PDIP-16	25 Unit / Rail
MC10H161PG	PDIP-16 (Pb-Free)	25 Unit / Rail

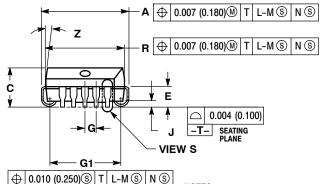
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

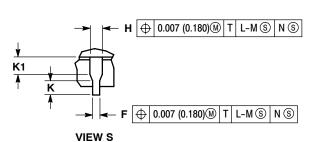
PACKAGE DIMENSIONS

20 LEAD PLLC CASE 775-02 **ISSUE E**









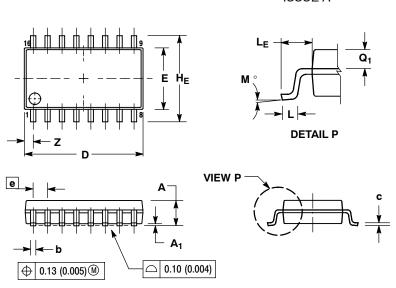
- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.
 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020	-	0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 **ISSUE A**



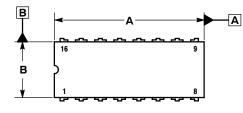
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

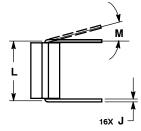
- NOTES:

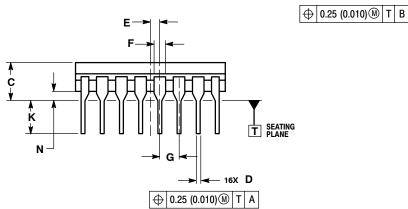
 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS AND ARE MEASURED
 AT THE PARTING LINE. MOLD FLASH OR
 PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
 PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD
 TO BE 0.46 (0.018).

	MILLIN	METERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.10	0.20	0.007	0.011	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10 °	0 °	10 °	
Q ₁	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

CDIP-16 **L SUFFIX** CERAMIC DIP PACKAGE CASE 620A-01 **ISSUE O**







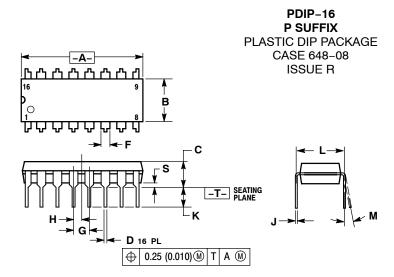
NOTES:

- DIMENSIONING AND TOLERANCING PER

- DIMENSIONING AND TOLEHARICING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
- BODY.
 THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100 BSC		2.54	BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10 °	0°	10 °
S	0.020	0.040	0.51	1.01

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